

Kulicke & Soffa To Present Technical Seminar at SEMICON West

SINGAPORE--(BUSINESS WIRE)-- Kulicke and Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company") will be holding a technical seminar during the SEMICON West trade show on July 15, 2015 at the Moscone Convention Center, North Lower Lobby, Room 124.

The following topics will be discussed:

- **Will the Electronics Industry Require More Accurate SMT Equipment or Faster Semiconductor Equipment?**
Presented by Alex Nies at 9:00 A.M.
The drive for smaller and thinner ICs, lower production costs and more complex packages are expected to drive demand for more advanced packaging production techniques in the pick and place market. Where most of today's existing SMT lines are still using the mature mass reflow processes, the more advanced and demanding production lines are looking for solutions to handle CSPs and flip chips with bump sizes down to 50µm or smaller. These types of advanced packages are new to the traditional SMT industry, but are already well known in the backend semiconductor industry.

The challenge will be either for the semiconductor equipment suppliers to increase the UPH, while maintaining the accuracy specification, or for SMT equipment suppliers to improve the accuracy while maintaining the UPH. A solution may be possible from each side. This presentation will attempt to examine the benefits and concerns of each.
- **Advanced Thermo-Compression Bonders Enable Lower Process Cost and Broad Capability.** Presented by Tom Strothmann and Bob Chylak at 10:00 A.M.
Recent advances in TC bonding equipment and processes have provided a significant increase in throughput and a lower total cost per unit for the technology. As a result, TCB is gaining traction as a high volume manufacturing technology and the preferred solution for many advanced products. This session will discuss the capability of current TCB equipment and the cost of TCB processes as compared to alternative assembly technologies. The equipment attributes and process developments that enable production to ramp to higher throughput, reliable performance, high yield and a high level of process data integration will be reviewed in detail.
- **Pushing the Limits of Wire Bonding.** Presented by John Foley at 2:00 P.M.
Wire bonding has been used for more than 60 years and remains the most widely used interconnect technology today. As demand for performance increases and applications become more complex, wire bonding continues to evolve and is capable of delivering the performance required at a lower cost and with more flexibility than other packaging alternatives. To stay relevant and competitive for the highest performance packages, wire bonding needs innovative solutions and improved process capability. For more cost sensitive devices, including QFN and memory, wire bonding delivers the highest productivity to help maintain lower package cost. This presentation will examine many of the recent advances in wire bonding, developed to meet the most challenging demands in today's packages.
- **Wedge Bonding Technology Trends and Improved Aluminum Wedge Bonding with Advanced Interconnects.** Presented by Chan Pin Chong at 3:00 P.M.
Kulicke & Soffa's PowerRibbon® interconnect technology is the leader in Aluminum ribbon wedge bonding due to its attractive combination of superior electrical performance, low manufacturing cost, process stability and high reliability. These benefits are driving adoption of PowerRibbon® technology for surface metallizations and die types traditionally bonded with multiple Al wires in order to improve equipment throughput, carry more current, and to dissipate greater heat for reliability enhancement. When combined with Kulicke & Soffa's long-life consumable products, PowerRibbon® technology provides inherent productivity improvement - with fewer bonds, customers gain higher yield and throughput.

Additionally, technology trends are expected to drive incremental Al ribbon adoption; examples include small power-semiconductor packages, such as Power Quad Flat-Pack No-Lead (PQFN), and industrial and automotive hybrid applications such as power modules for popular hybrid cars. This presentation will focus on the technology benefits and opportunities for PowerRibbon® adoption.

Customers can register for the technical seminar through the Company's website (<http://www.kns.com/en-us/Pages/Trade%20Shows.aspx>).

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a

broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

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Kulicke & Soffa Industries, Inc.

Sheila Frese

Public Relations

P: +1-949-399-2930

F: +1-949-660-0444

sfrese@kns.com

or

Kulicke & Soffa Industries, Inc.

Investor Relations

P: +1-215-784-7500

F: +1-215-784-6180

investor@kns.com

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